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(19) **United States**(12) **Patent Application Publication**  
**SCHMID et al.**(10) **Pub. No.: US 2022/0369495 A1**(43) **Pub. Date: Nov. 17, 2022**(54) **COOLING DEVICE FOR A POWER  
ELECTRONICS MODULE WITH COOLING  
ADAPTER, POWER ELECTRONICS  
MODULE AND MOTOR VEHICLE****Publication Classification**(51) **Int. Cl.**  
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CPC ..... **H05K 7/209** (2013.01)(71) Applicant: **Bayerische Motoren Werke  
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(57) **ABSTRACT**

A cooling device for a power electronics module for cooling a power electronic assembly of the power electronics module includes a heatsink for dissipating waste heat from at least one power electronic component arranged on a circuit board, and at least one heat-conducting element for providing a local heat-conducting path between the at least one power electronic component and the heatsink. Heat-conducting element is formed as a cooling adapter and is separate from the heatsink and has a heat-conducting core, which can be arranged between the heat sink and the power electronic assembly and is designed to bridge a distance between the at least one power electronic component and the heatsink.

